

HONHEVER(HK)LIMITED

ITEM :

CRYSTAL RESONATOR

TYPE :

DSX321G

NOMINAL FREQUENCY :

8.000MHz

SPEC No. :

1C208000BC0R

Please acknowledge receipt of this specification by signing and returning a copy to us.

	RECEIPT
DATE	
RECEIVED	(signature) (name)



1. ELECTRICAL CHARACTERISTICS

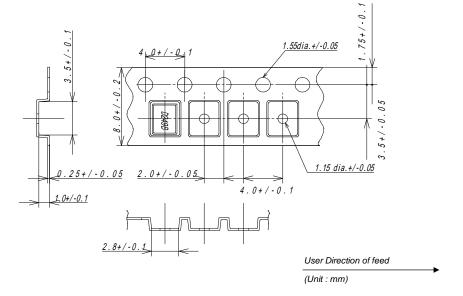
(This test shall be performed under the conditions of temp.at +25 \pm 3°C, Relative Humidity 60% max.)

	temp.at 125 1 5 C, Relative Humidity 00 // max.)
(1) NOMINAL FREQUENCY	8.000000 MHz	
(2) OVERTONE ORDER	Fundamental	
(3) LOAD CAPACITANCE(CL)	12.0 pF	
(4) FREQUENCY TOLERANCE	±20 ppm max. (at +25 ± 3 °C)	
(5) DRIVE LEVEL	10 ± 2 µW	
(6) SERIES RESISTANCE	400 Ω max. (at Series)	
(7) OPERATING TEMPERATURE RANGE	-40 ~ +85 °C	
(8) FREQUENCY CHARACTERISTICS OVER TEMPERATURE	±30 ppm max. / -40 ~ +85 °C	(ref. to +25°C)
(9) SHUNT CAPACITANCE	2.0pF max.	
(10) INSULATION RESISTANCE	$500 M\Omega$ min. / DC 100 \pm 15V	
(11) STORAGE TEMPERATURE RANGE	-40 ~ +85 °C	
2. CONSTRUCTION (1) DIMENSIONS AND MARKING	Refer to 4.	
3. OTHER SPECIFICATIONS (1) EMBOSS CARRIER TAPE & REEL	Refer to 5.	
(2) PACKING	Refer to 6.	
(3) REFLOW CONDITIONS (REFERENCE)	Refer to 7.	
(4) LAND PATTERN (REFERENCE)	Refer to 8.	
(5) RELIABILITY SPECIFICATION	Refer to 9. ~ 11.	
(6) OTHER HANDLING INSTRUCTIONS	Refer to 12.	
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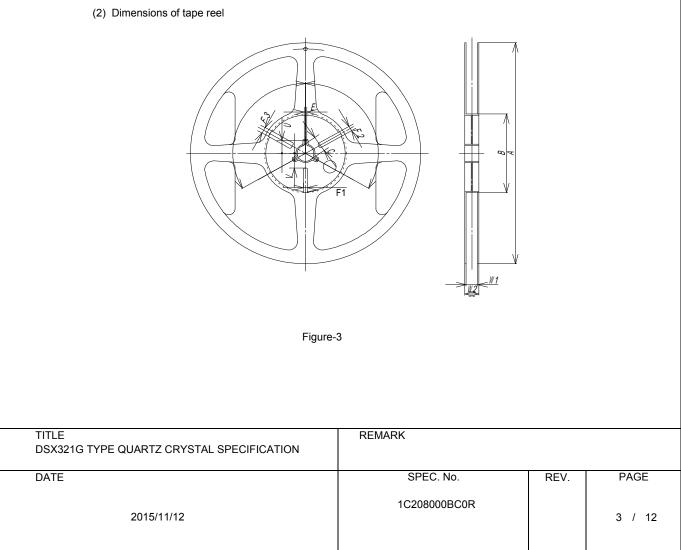
4. DIMENSIONS AND MARKING		
	ernal connections)	
	View> # 3 #1 ,#3 Connecte #2 ,#4 Open (un	d to quartz element connected)
	# 2 Unit : mm Tolerance : ±0.1	
Figure-1		
Logo(1) and Nominal Frequency (2) should be print	ed as follows by producing district	
Made in INDONESIA> Spec. No.:	1C208000CE0Q ,Logo: <u>D</u> , Free	quency: 08
	* Made in INDONESIA	: Under Bar with D
Nominal Frequency (2) = Mark two digits from uppe (ex. 8.000000 MHz> 08)	er decimal point	
	' 5 ' (The last digit of the year) ' L ' (As shown in Table-1.)	
(Table-1.)		
MonthJan.Feb.Mar.Apr.May.MarkABCDE	Jun.Jul.Aug.Sep.Oct.FGHJK	Nov. Dec. L M
Plating material of a terminal. : Ni Plating + Au Platir A clearance between the soldering terminal portion a		than 0.1mm.
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5. EMBOSS CARRIER TAPE & REEL

(1) Dimensions of embossed carrier tape







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(Unit:mm)					
	Item			Dimensions Angle	
	Diameter		А	Ф180 +0.0 / -3.0	
_	Inside	of Frange	W1	9.0 ± 0.3	
Flange	Outsid	e of Frange	W2	11.4 ± 1.0	
	Inside Diameter		В	Ф60 +1.0-0	
	Center Core Slit	Width	F1	3.0 ± 0.2	
			F2	4.0 ± 0.2	
			F3	5.0 ± 0.2	
		Length	V	11.9 +0.5 / -0.0	
Center Core		Angle	θ	120°	
	Spindle Diameter		С	Φ13 ±0.2	
		Width	E	2.0 ± 0.5	
	Key Seats	Length	U	10.5 ± 0.4	
		Angle	θ	120°	

(3) Material of the reel

Reel	Polystyrene+Carbon(Black)		
	Polystyrene(White)		

(4) Storage condition

Temperature : +40 °C max.

Relative Humidity : 80% max.

(It is a guaranteed term because it obtains an excellent soldering: 6 months)

(5) Standard packing quantity

3,000 pcs/reel

(6) Material of the tape

Таре	Material		
Carrier tape	Polystyrene+Carbon		
Cover tape	Polyester		

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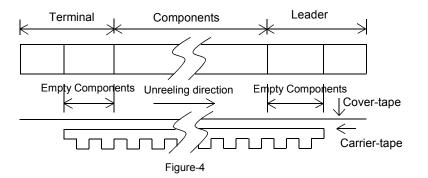
(7) Label contents

Type Our specification No. Your Part No. Lot No. Nominal Frequency Quantity Our Company Name Producting Country

Stick a label on the each reel.

(8) Taping dimension

	Cover-tape	The length of cover-tape in the leader is more than 400mm
Leader		including empty embossed area.
	Carrier-tape	After all products were packaged, must remain more than twenty pieces
		or 400mm empty area, which should be sealed by cover-tape.
	Cover-tape	The tip of cover-tape shall be fixed temporary by paper tape and roll around
Terminal		the core of reel one round.
	Carrier-tape	The empty embossed area which are sealed by cover-tape must remain
		more than 40mm.



- (9) Joint of tape
 - The carrier-tape and cover-tape should not be jointed.
- (10) Release strength of cover tape
- It has to between 0.1 ~ 0.7N under following condition. Pulling direction 165 ~ 180 ° Speed 300mm/min Otherwise unless specified.

165 ~ 180 ° Pulling direction

Figure-5

Other standards shall be based on JIS C 0806 _1990.

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6. PACKING

(1) STORAGE METHOD

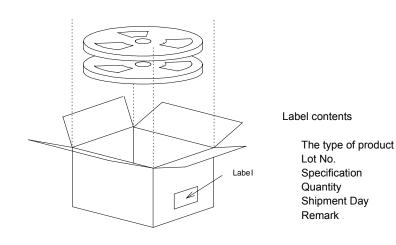


Figure-6

(2) BOX SIZE

From lot size packingsize shall be changed. In the upper and lower part and the opening in box it shall be protected products using aircushion sheets.

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7. REFLOW CONDITIONS (REFERENCE)

During the solder reflow process, please complete within following temperature, period. Reflow soldering shall be allowed only 3 times.

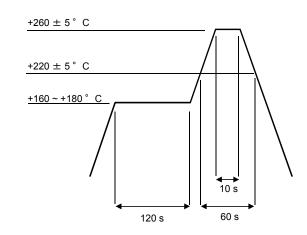


Figure-7

Total time : 240 s max.

HANDSOLDERING METHOD : +350 \pm 10 °C , 3+1/-0s Each terminal once (Please take care so that a soldering iron should not touch a product directly.)

8. LAND PATTERN (REFERENCE)

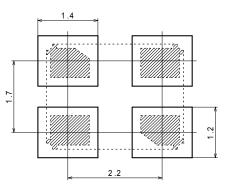


Figure-8

Unit : mm

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9. MECHANICAL ENDURANCE

(1)	SHOCK	(ACCEL	ERATION	1)			
	After the	following	test,parts	shall c	onform s	specific	ation 11.C
	1000m/s	² by 6ms	X,Y,Z ea	ch axis	(6 direct	ions),	3cvcles

(2) SHOCK (MOUNTING DROP)

After the following test, parts shall conform specification 11.C 3cycles(18times) drop from 150 cm heights to concrete.

Further, parts shall be solderd on substrate, fixed Aluminum materials (about 100g).

- Substrate materials : Glass Epoxy
- 1 cycle : each 1 times of 6 directions

(3) VIBRATION

After the following test, parts shall conform specification 11.C and no abnormal appearance shall be observed.

Frequency of Vibration	:	10 ~ 500 ~ 10 Hz
Amplitude(p-p)	:	Sine waves of 1.5mm or 100m/s ²
Cycle	:	11min
Vibration axis	:	X.Y.Z
Vibration period	:	2 h for each axis

(4) SEAL

Less than 2.0×10^{-9} Pa m³/s by Helium leak detector. Also, no serial bubble is observed by Fluorocarbon tests.

(5) SOLDERABILITY

After the following test, more than 95% of terminal shall be covered by new solder. 3 ± 0.5 s dip in +245 ± 5 °C solder. (Solder composition : Sn-3Ag-0.5Cu) (Use rosin type flux for solder.)

(6) RESISTANCE TO SOLDERING HEAT (REFLOW) 48 h past at room temperature from following test, parts shall conform specification 11.C perform the attached Reflow conditions to reference.

(7) RESISTANCE TO SOLDERING HEAT (HAND SOLDERING METHOD) 48 h past at room temperature from following test, parts shall conform specification 11.C +350 ± 10°C , 3+1/-0s Each terminal once.

(8) SUBSTRATE BENDING

After the following test, parts shall conform specification 11.C and no abnormality shall be observed in external appearance and sealing tightnen and others shall be based on ET-7403 of EIAJ.

Mount the specimen on substrate.

Apply the following pressure	
Direction	:

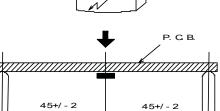
Amount of substrate

Direction	-	see right figure
Speed	:	about 1.0 mm/s
Hours	:	5±1s

: 3 mm max.

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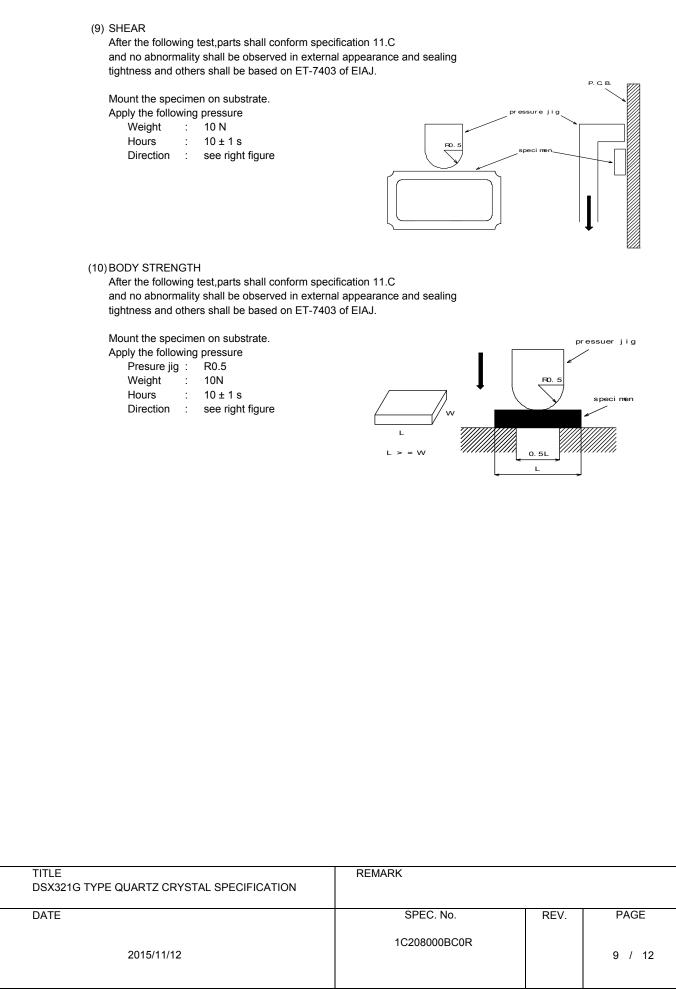
pressure jig



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10. ENVIRONMENTAL ENDURANCE

(1) LOW TEMPERATURE

2 h past at room temperature after following test, parts shall conform specification 11.C 240 h , -40 \pm 3 °C.

(2) HUMIDITY

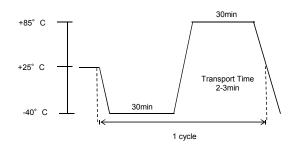
2 h past at room temperature after following test, parts shall conform specification 11.D 240 h , +85 \pm 2 °C , relative humidity 85 \pm 5%.

(3) HIGH TEMPERATURE

2 h past at room temperature after following test, parts shall conform specification 11.D 240 h , $\ \ +85\pm 2$ °C.

(4) TEMPERATURE CYCLE

2 h past at room temperature after 25 cycles of following test, parts shall conform specification 11.D



11. SPECIFICATION

Frequency Variation and Equivalent Resistance shall be within Table below after the reliability test.

Spec.	ec. Frequency Variation Equivalent Resistance			
Α	A $\pm 2ppm$ $\pm 15\%$ or 2.0 Ω max. (Use larger specification)			
В	B ±5ppm ±15 % or 2.0 Ω max. (Use larger specification)			
С	± 20 % or 3.0 Ω max. (Use larger specification)			
D	D ± 10 ppm ± 20 % or 3.0 Ω max. (Use larger specification)			
E	±20ppm	± 25 % or 10.0 Ω max. (Use larger specification)		

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12. DSX321G TYPE QUARTZ CRYSTAL HANDLING INSTRUCTIONS

(1) SOLDERING

Please perform the attached Reflow conditions to reference within 3 times.

(2)	MOUNT
	Crystal products are designed to be compatible with automatic mounting.
	Be sure to have a mounting test in advance by using the actual mounting machine
	and check that the characteristics of the products are not damaged
	by the automatic mounting.
	In the process where the boad is warped, such as board separation process,
	be careful that the warping does not influence the characteristics
	and soldering of crystal products.
	Since mounting by Ultrasonic welding and processing have a possibility of an excessive
	vibration spreading inside a crystal resonator and becoming the cause of characteristic
	deterioration and not oscillating, it does not recommend.
	Underfilling Material for DSX321G Types,KDS considers underfilling material such as heat-cured resin
	would not affect the characteristics of the DSX321G crystal mounted, however, we recommend the crystal
	be tested and checked in such a case prior to use so that there are the possibility that the crystal may have
	a lid off or a crack in the ceramic base.
(0)	
(3)	WASHING
	About use of the washing liquid of a basin system,
	an alcoholic system, and a chlorofluorocarbon-replacing
	material system, it is checking that it is satisfactory.
	However please consult in advance about other washing liquid.
	Although the check about ultrasonic washing is performed,
	since it is an examination with a simple substance,
	the check for the second time by the use state is recommended.
(4)	THE CAUTIONS ON USE
()	The piece of crystal it is processed very smaller than the conventional thing
	inside DSX321G series crystal unit may be damaged.
	if excessive excitation electric power is applied.
	Please use it below with the value specified on a catalog and specifications.
	Please refrain from forming patterns between crystal land pattern's since there is
	a possibility to cause crack in base.
	If the temperature is higher than +280 °C, there is a possibility for the sealing glass to remelt.
	Avoid using the product at temperature higher than specified.
(5)	HANDLING OF A PRODUCT
	DSX321G series has sufficient intensity to fall and vibration.
	However when too much shock is added according to a certain cause,
	the use after a characteristic check is recommended.

(6) STORAGE

Since the soldering nature of a terminal may be degraded, please avoid storage in high temperature and a humid place. Please keep it in the place which direct rays do not hit and dew condensation does not generate.

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Rev.No	Date	Reason	Contents	Approved	Checked	Drawn
-	2015/11/12	-	The first edition.	T.Kusai		S.Miura

2015-111F REVISION RECORD